GH6C605B3A/GH6C605B3B GH6C605B5A/GH6C605B5B

Features

- (1) With built-in high speed response OPIC* (MIN. 40MHz)
- (2) For CD-ROM drives (equivalent to ×40 speed)
- (3) Insert frame structure enables easy mounting compared to conventional pin structure.
- (4) Thin and compact package enables thin and compact pick-up design.

GH6C605B3A/B: 4.8mm thickness GH6C605B5A/B: 3.0mm thickness

(5) With built-in beam splitter and diffraction grating

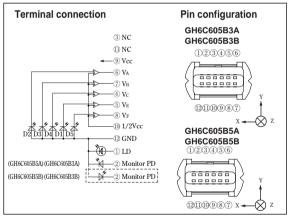
*OPIC: (Optical IC) is a trademark of SHARP Corporation. An OPIC consists of a light-detecting element and a signal-processing circuit integrated onto a single chip.

Model No.

- GH6C605B3A/GH6C605B5A Dual power supply
- GH6C605B3B/GH6C605B5BSingle power supply

Applications

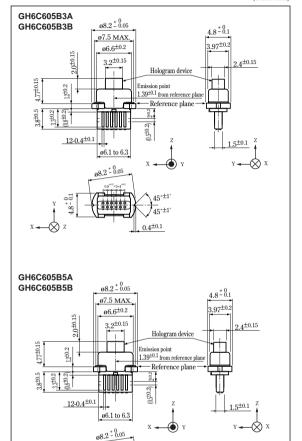
- (1) DVD-ROM drives
- (2) CD-ROM drives for notebook PCs



Resin type Hologram Laser for CD-ROM Drive(Equivalent to X40 Speed)

Outline Dimensions

(Unit:mm)



Absolute Maximum Ratings

	Parame	eter	Symbol	Rating	Unit
*1	*1 Optical power output			4.3	mW
	Dovomas violtama	Laser	V_R	2	V
	Reverse voltage	Monitor photodiode	VR	30	V
	OPIC supply voltag	e	Vcc	6	V
*2	Operating temperat	ure	Topr	-10 to +70	°C
*2	Storage temperatur	e	Tstg	-40 to +85	°C
*3	Soldering temperat	ure	Tsold	260	°C

- *1 Output power from hologram laser, CW (Continuous Wave) drive
- Case temperature
- At the position of 1.6mm from the lead base (Within 5s)

SHARP

(Tc=25°C)

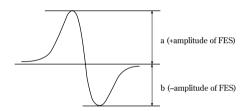
Electro-optical Characteristics

(Vcc=5V, Tc=25°C)

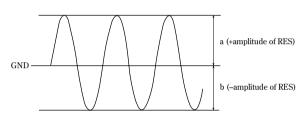
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
*1 Focal offset		DEF	V_{RF} =0.55 V	-0.7	-	+0.7	μm
*2 Focal error sym	metry	Bres	V_{RF} =0.55 V	-25	-	+25	%
*3 Radial error bala	ance	Bres	P _H =3.0mW	-25	-	+25	%
**4 RF output ampli	tude	V_{RF}	P _H =3.0mW	0.42	1.00	-	V
*5 FES output amp	litude	VFES	V_{RF} =0.55 V	0.23	0.35	0.47	V
**6 RES output amplitude		Vres	V_{RF} =0.55 V	0.08	0.12	0.16	V
Threshold current		Ith	-	-	25	39	mA
Operating curre	Operating current		P _H =3.0mW	-	36	50	mA
Operating voltag	ge	V_{op}	P _H =3.0mW	-	1.85	2.2	V
Wavelength		λ_{p}	P _H =3.0mW	770	780	795	nm
Output oument	GH6C605B3A/GH6C605B5A		D 00 W V 15V	0.06	0.32	0.60	mA
Output current	GH6C605B3B/GH6C605B5B	I_{m}	P _H =3.0mW, V _R =15V	0.05	0.2	0.60	mA
Differential efficiency		ηd	2.0mW I(3.0mW)-I(1.0mW)	0.17	0.27	0.55	mW/mA

^{*1} Distance between FES=0 and jitter minimum point At the condition of FES sensitivity = 20%/1µm

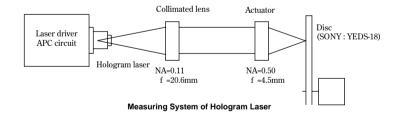
(a-b) / (a+b)







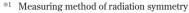
- **4 Amplitude of Va+VB+2Vc (focal servo ON, radial servo ON)
- *5 VA-VB (Focal vibration)
- *6 VE-VF (focal servo ON, radial servo OFF)

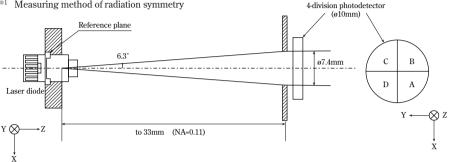


Electro-optical Characteristics of Laser Diode (Design Standard*)

(Tc=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Emission	*1 Symmetry	Parallel	S//	S// D. O. W. L. MA 0.11		-	+25	%
characteristics	Symmetry	Perpendicular	S⊥	Po=3mW, Into NA=0.11	-15	-	+15	%
Misalignment position		Δx	_	-80	-	+80	μm	
		Δy		-80	-	+80	μm	
		Δz		-80	-	+80	μm	
Interference pattern intensity		α	Po=3mW	-	1	0.99	-	





Parameter	Definition
S//	$\frac{(P_{\rm B} + P_{\rm C}) - (P_{\rm A} + P_{\rm D})}{P_{\rm A} + P_{\rm B} + P_{\rm C} + P_{\rm D}}$
s⊥	$\frac{(P_A + P_B) - (P_C + P_D)}{P_A + P_B + P_C + P_D}$

Px: Output of light detector X

Electrical Characteristics of Monitor Photodiode (Design Standard*) (GH6C605B3A/GH6C605B5A)

(Tc=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
**2 Sensitivity	S		-	0.11	-	mA/mW
Dark current	ID	$V_R=15V$	-	-	150	nA
Terminal capacitance	Ct		-	3.5	-	pF

(GH6C605B3B/GH6C605B5B)

(Tc=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
*2 Sensitivity	S		-	0.07	-	mA/mW
Dark current	ID	V _R =15V	-	-	150	nA
Terminal capacitance	Ct		-	7.7	-	pF

For hologram output power

Electro-optical Characteristics of OPIC for Signal Detection (Design Standard*)

(Tc=25°C)

		_	-	_	-		
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	*3 Segment
Supply voltage	Vcc		4.5	5	5.5	V	
Supply current	Icc	Vcc=5V	6	9	12	mA	
*4 Output offset voltage	Von		-25	0	+25	mV	VA, VB, VC
Output onset voltage	VOD	Vcc=5V	-15	0	+15	mV	Ve, Vf
Off+1+ 1:ff	erence AVon	No light	-25	0	+25	mV	Va-VB
Offset voltage difference	Δνου		-15	0	+15	mV	VE-VF
D	fcF	**5 Vcc=5V, -3dB	40	55	-	MHz	VA, VB, VC
Response frequency	fcr	R _L =10kΩ, CL=10pF	5	7	-	MHz	Ve. Ve

Applicable divisions correspond to output terminals.

*4 Difference from Vcc/2

*5 Output amplitude=0dB (input signal 100kHz) BW=10kHz

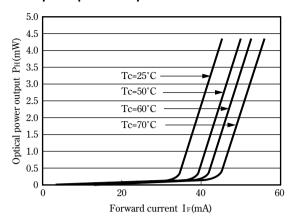
D1	
D2	D4
D3	D4
D5	

Segment No.	Output
D 1	$V_{\rm E}$
D 2	V _A
D 3	V _B
D 4	Vc
D 5	V _F

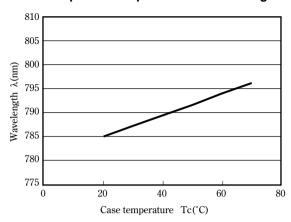
^{*} These parameters are not guaranteed performance, but general specifications of each optical element which makes up a hologram laser.

[•] Please refer to the chapter "Handling Precautions"

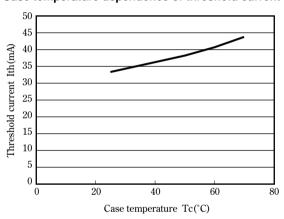
Optical power output - Forward current



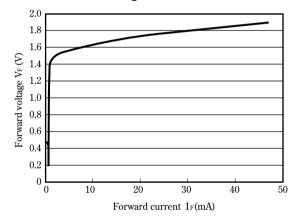
Case temperature dependence of wavelength



Case temperature dependence of threshold current



Forward voltage - Forward current



Note) Characteristics shown in diagrams are typical values. (not assurance value)

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